产品承认书
SPECIFICATION FOR APPROVAL

客户名称:
CUSTOMER

我司料号:
OUR PART NO. **XRPQ3220J-220M**

我司品名:
OUR PART NAME **PQ inductor**

送样日期:
DATE SAMPLES

数 量:
QUANTITY

制造确认 MANUFACTURER APPROVE		
拟制 DRAWN	审核 CHECKED	确认 APPROVED
Hu Fangting	RaoPing	LiZhengxiong

客户确认 CUSTOMER APPROVE

客户名称 CUSTOMER NAME:

客户料号 CUSTOMER P/N:

规格型号 DESCRIPTION: PQ3220J 22uH ±20% 19A

检查結果: □ 合格 □不合格 签名及盖章:

INSPECT RESULT ACCEPT REJECT SIGNATURE AND STAMP

说明 REMARK:

如对本承认书内容有异议请提出或标记发送至我司，本承认书在未收到异议回复时于本承认书提供一周后生效。

If you have any objection to the contents of this acknowledgment, please raise it or send the mark to us. The acknowledgment will become effective one week after the acknowledgment is provided in the absence of any objection.

东莞市祥如电子有限公司

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产品承认书
SPECIFICATION FOR APPROVAL

客户名称 CUSTOMER		日期 DATE	2026/3/15
客户物料编号 CUSTOMER P/N		客户规格型号 DESCRIPTION	PQ3220J 22uH ±20% 19A
我司物料编号 OUR PART NO	XRPQ3220J-220M	我司品名 OUR PART NAME	PQ inductor

修订记录 Revision record

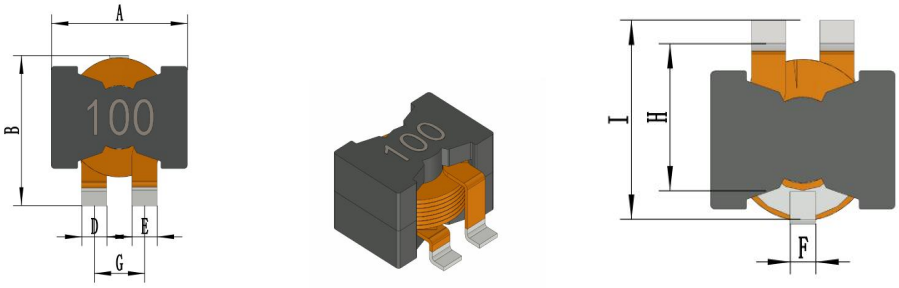
日期 Date	修改内容 Modify the content	审核 Checked	确认 Approved
2026/3/15	首次发行First issue	ZhongCuilan	HuangChuangen

产品承认书
SPECIFICATION FOR APPROVAL

客户名称 CUSTOMER		日期 DATE	2026/3/15
客户物料编号 CUSTOMER P/N		客户规格型号 DESCRIPTION	PQ3220J 22uH ±20% 19A
我司物料编号 OUR PART NO	XRPQ3220J-220M	我司品名 OUR PART NAME	PQ inductor

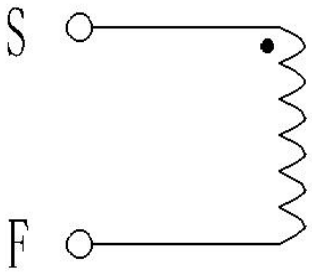
外观尺寸 Appearance of size：

单位 Unit：mm



A	B	C	D	E	F	G	H	I	印字
32.5±1.0	34.5MAX	20.0±1.0	6.0±0.3	6.0±0.3	4.5±0.3	12.0±0.5	23.6±0.5	32.0±0.5	220

电路图SCHEMATICS:



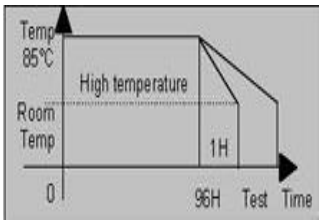
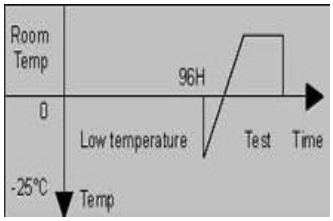
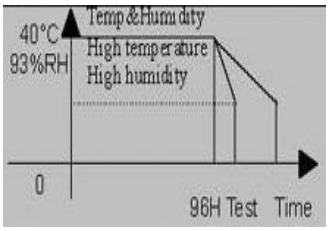
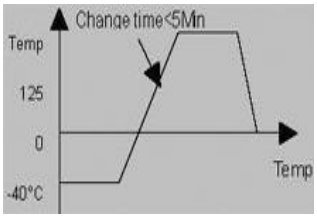
ELECTRONICAL CHARACTERISTIC:

ITEM	Spec.	Test Frequency
电感值L	22uH±20%	100KHz/0.25V
直流电阻DCR	1.8mΩMAX	25℃
额定电流	19A（drop≤35%）	100KHz/0.25V

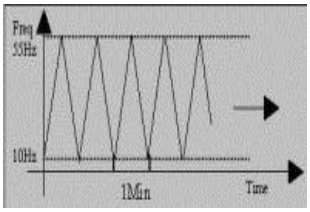
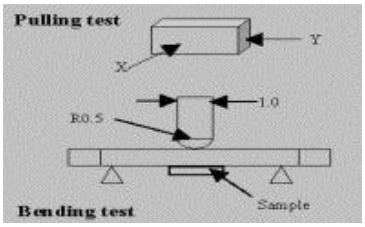
MAIN MATERIALS LIST:

NO.	DESCRIPTION	MATERIAL
1	WIRE	1*6*14*7.75TS
2	DRCORE	PC96-PQ3220
3	RI CORE	PC96-PQ3220-磨气隙
4	CLIP	PQ32假脚
5	EPOXY	E107 / J331
6		
7		

可靠性测试
Reliability Testing

Item (項目)	Required Characteristics (要求)	Test Method/Condition (测试方法)
High temperature Storage test Reference documents: MIL-STD-202G Method 108A 高温存储实验	1.No case deformation or change in appearance. 2.ΔL/L≦10% 3.ΔQ/Q≦30% 4.ΔDCR/DCR≦10%	Temperature: 85±2℃ Time : 96±2 hours Tested not less than 1 hour, nor more than 2 hours at room temperature. 溫度: 85±2℃,时间: 96±2,小时样品在室溫下放置1小时,不 超2小时间必须测试. 
Low temperature Storage test Referencedocuments: IEC 68-2-1A 6.1 6.2 低温存储实验	1.No case deformation or change in appearance. 2.ΔL/L≦10% 3.ΔQ/Q≦30% 4.ΔDCR/DCR≦10%	Temperature: -25±2℃ Time : 96±2 hours Tested not less than 1 hour, nor more than 2 hours at room temperature. 溫度: -25±2℃,时间:96±2,小时样品在室溫下放置1小时,不 超2小时间必须测试. 
Humidity test Reference documents: MIL-STD-202G Method 103B 温度测试	1.No case deformation or change in appearance. 2.ΔL/L≦10% 3.ΔQ/Q≦30% 4.ΔDCR/DCR≦10%	1. Dry oven at a temperature of 40° ±5°C for 24 hours. 2. Measurements At the end of this period 3. Exposure:Temperature: 40±2℃ , 
Thermal shock test Reference documents: MIL-STD-202G Method 107G 热冲击测试	1.No case deformation or change in appearance. 2.ΔL/L≦10% 3.ΔQ/Q≦30% 4.ΔDCR/DCR≦1	First -40℃forT time, last125℃T time as 1 cycle. Go through 20 cycles. 从-40°C作用T分钟,然后温度冲击到125°C作用T分钟,作为一个循环,共作用20次. 

可靠性测试
Reliability Testing

Item (項目)	Required Characteristics (要求)	Test Method/Condition (测试方法)
Solderability test Reference documents:MIL-STD-202G Method 208H IPC J-STD-002B 可焊性测试	Terminals area must have 95% min. Solder coverage 端子必须有95%以上著锡	Dip pads in flux then dip in solder pot at 260±5°C for 5 second. Solder:Lead free
Heat endurance of Reflow soldering Reference documents:IPC J-STD-020B过再流焊测试	1.No case deformation or change in appearance. 2.ΔL/L≦10% 3.ΔQ/Q≦30% 4.ΔDCR/DCR≦10%	Refer to the next page reflow curve Gothrough 3 timesThe peak temperature : 260±5℃ 参照下页回流焊曲线过三次
Vibration test Reference documents:MIL-STD-202G Method 201A 振动测试	1.No case deformation or change in appearance. 2.ΔL/L≦10% 3.ΔQ/Q≦30% 4.ΔDCR/DCR≦10%	Apply frequency 10~55Hz. 0.75mm amplitude in each of perpendicular direction for 2 hours.(total 6 hours)用10~55Hz 振动频率0.75mm振幅沿X,Y,Z方向各振动2小时.(共6小时) 
Drop test Reference documents: MIL-STD-202G Method 203C 落下测试	1.No case deformation or change in appearance. 2.ΔL/L≦10% 3.ΔQ/Q≦30% 4.ΔDCR/DCR≦10%	Packaged & Drop down from 1m with 981m/s2(100G) a ttitude In 1 angle 1 ridges & 2 surfaces orientations. 将产品包装后从1米高度自然落下至试验板上
Terminal strength push test Reference documents:JIS C 5321:1997 端子强度测试	Pulling test: DEFINE: A: sectional area of terminal A≦8 (Sq M) force≧5N time:30sec 8(Sq M) <A≦20(Sq M	Bend the testing PCB at middle point,the deflection shall be 2mm 将PCB对中弯折,到达挠度2mm 
Resistance to solvent test Reference documents: IEC 68-2-45:1993 耐溶剂性测试	No case deformation or change in appearance,or obliteration of marking 无外观破坏及标记破损	To dip parts into IPA solvent for 5±0.5Min, then drying them atroom temp for 5Min,at last ,to brushing making 10 times. 在IPA溶剂中浸泡5±0.5分钟,室温下干燥5分钟,然后擦拭10次.